

CHIPLINK DUAL N-Channel Enhancement Mode Power MOSFET

Description

The LX8205A combines advanced trench technology to provide excellent $R_{DS(ON)}$. This device is suitable for use as battery protection or a load switch application.

Features

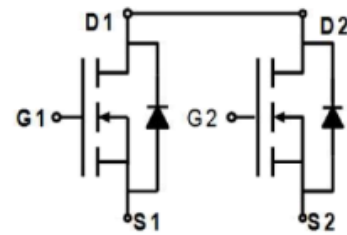
- $V_{DS}=20V$, $I_D=5A$
 $R_{DS(ON)} < 29m\Omega @ V_{GS}=4.5V$
 $R_{DS(ON)} < 34m\Omega @ V_{GS}=2.5V$
- High power and current handing capability
- Common drain configuration for design simplicity
- Termination is Lead-free and RoHS Compliant



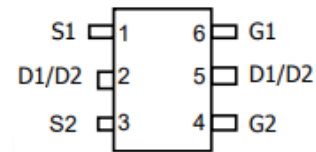
Applications

- Battery protection switch
- Load switch

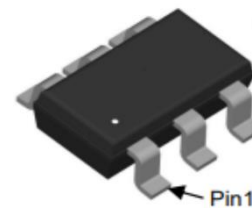
Schematic Diagram



Pin Assignment



SOT23-6 Package



Maximum Ratings($T_A=25^{\circ}C$ unless otherwise noted)

Parameter	Symbol	Maximum	Units
Drain-Source Voltage	V_{DS}	20	V
Gate-Source Voltage	V_{GS}	± 8	V
Continuous Drain Current	I_D	6	A
Pulsed Drain Current ^B	I_{DM}	20	A
Maximum Power Dissipation ^A	P_D	1.25	W
Junction and Storage Temperature Range	T_J, T_{STG}	-55 To 150	$^{\circ}C$

Thermal Characteristic

Thermal Resistance, Junction to Ambient	R_{QJA}	100	$^{\circ}C/W$
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Electrical Characteristics ($T_A=25^{\circ}\text{C}$ unless otherwise specified)

Parameter	Symbol	Test conditions	MIN	TYP	MAX	UNIT
Drain-Source Breakdown Voltage	BV _{DSS}	V _{GS} =0V, I _D =250uA	20			V
Gate-Threshold Voltage	V _{th(GS)}	V _{DS} = V _{GS} , I _D =250 uA	0.45	0.6	1	V
Gate-body Leakage	IGSS	V _{DS} =0V, V _{GS} =±8V			±100	nA
Zero Gate Voltage Drain Current	IDSS	V _{DS} =20V, V _{GS} =0V			1	uA
Drain-Source On-Resistance	R _{DS(ON)}	V _{GS} =4.5V, I _D =2.5A		20	25	mΩ
		V _{GS} =2.5V, I _D =2.0A		25	35	mΩ
Forward Transconductance	g _{FS}	V _{DS} =5V, I _D =1.0A		18		s
Dynamic Characteristics						
Input Capacitance	C _{iss}	V _{DS} = 10V, V _{GS} =0V, F=1MHz		418		pF
Output Capacitance	C _{oss}			82		
Reverse Transfer Capacitance	C _{rss}			70		
Switching Capacitance						
Turn-on Delay Time	t _{d(on)}	V _{DD} = 10V, R _L =2.9Ω V _{GS} = 4.5V, R _{GEN} =3Ω		4.2		nS
Turn-on Rise Time	t _r			19.8		nS
Turn-off Delay Time	t _{d(off)}			22.6		nS
Turn-off Fall Time	t _f			20		nS
Total Gate Charge	Q _g	V _{DS} = 10V, I _D =2A, V _{GS} =4.5V		10.5		nC
Gate-Source Charge	Q _{gs}			5		nC
Gate-Drain Charge	Q _{gd}			2.5		nC
Drain-Source Diode Characteristics						
Diode Forward Voltage	V _{SD}	V _{GS} =0V, I _D =5A			1.2	V
Diode Forward Current	I _s				5.0	A

Notes:

- The Power dissipation P_D is based on $T_{J(MAX)}=150^{\circ}\text{C}$, using $\leq 10s$ junction-to ambient thermal resistance.
- Repetitive rating, pulse width limited by junction temperature $T_{J(MAX)}=150^{\circ}\text{C}$. Ratings are based on low frequency and duty cycles to keep initial $T_J=25^{\circ}\text{C}$.
- The Static characteristics in Figures are obtained using $<300\mu s$ pulses, duty cycle 2% max.

Typical Electrical and Thermal Characteristics

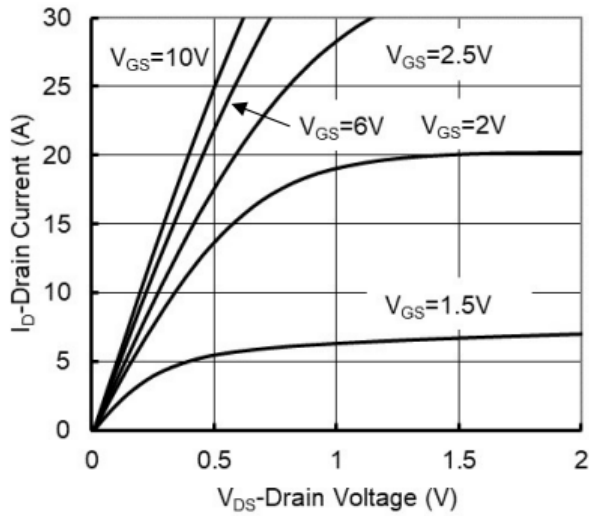


Figure1. Output Characteristics

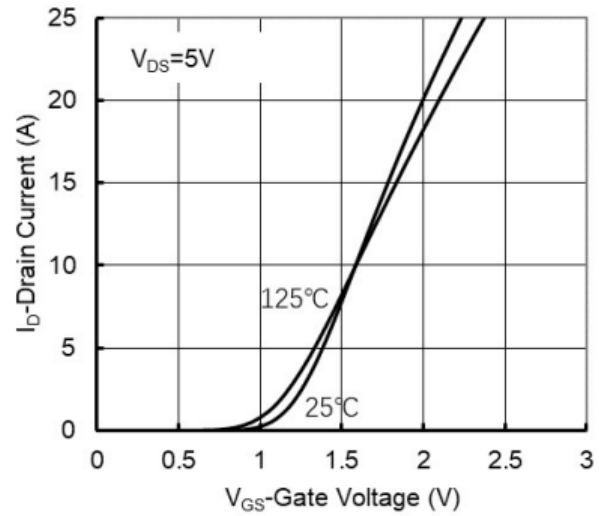


Figure2. Transfer Characteristics

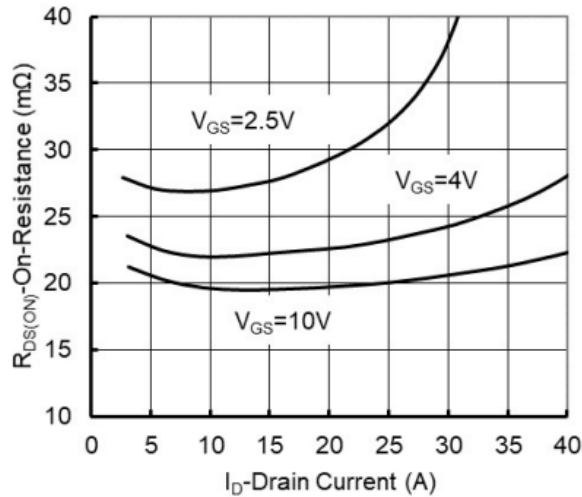


Figure 3: On-Resistance vs. Drain Current and Gate Voltage

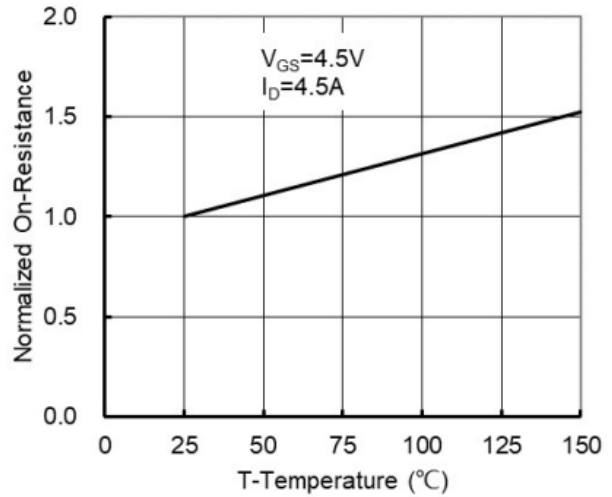


Figure 4: On-Resistance vs. Junction Temperature

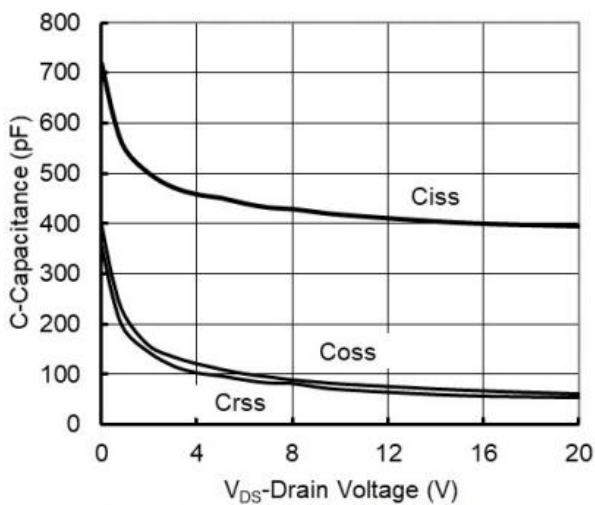


Figure5. Capacitance Characteristics

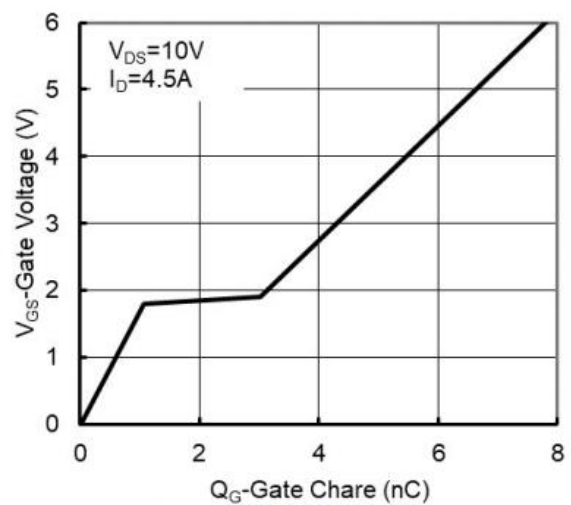


Figure6. Gate Charge

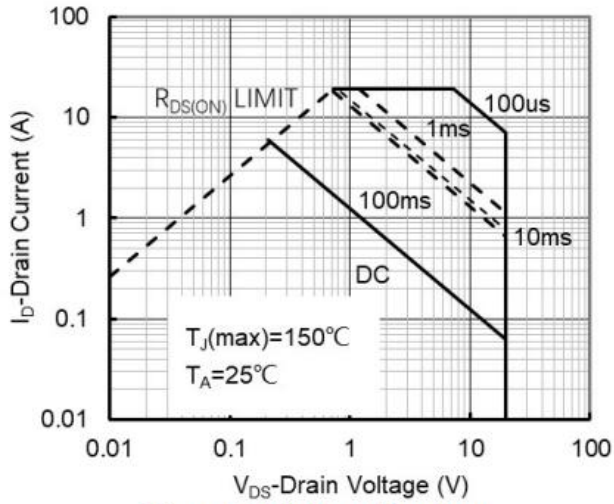


Figure7. Safe Operation Area

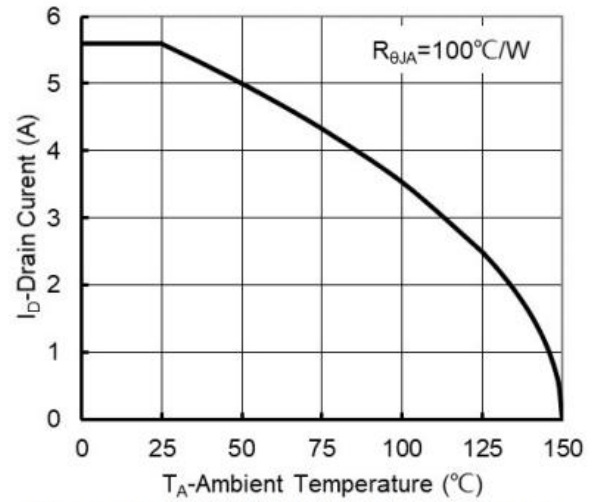


Figure8. Maximum Continuous Drain Current vs Ambient Temperature

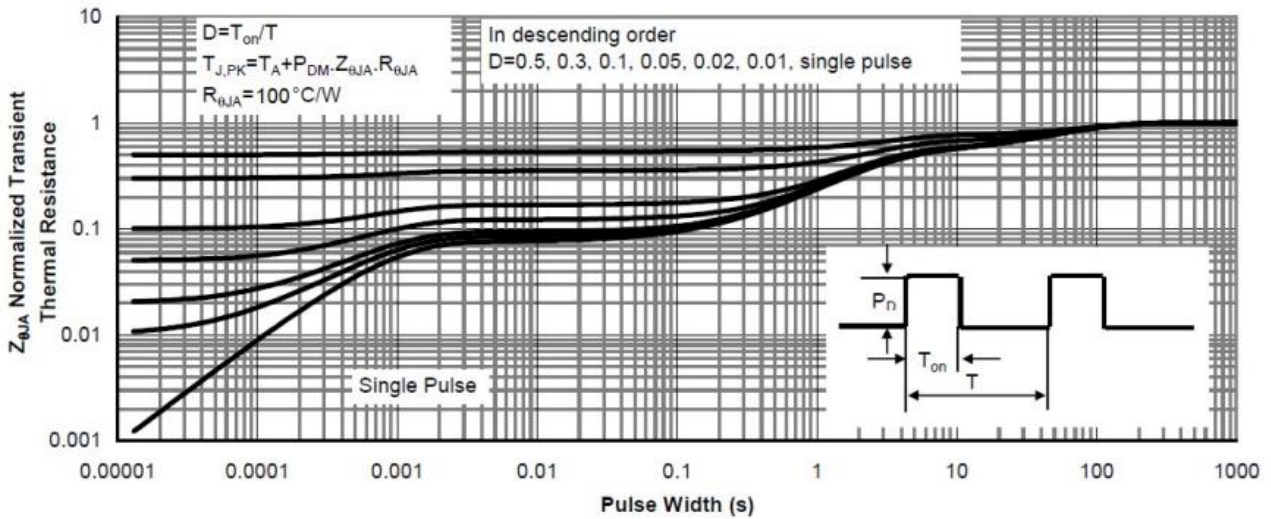
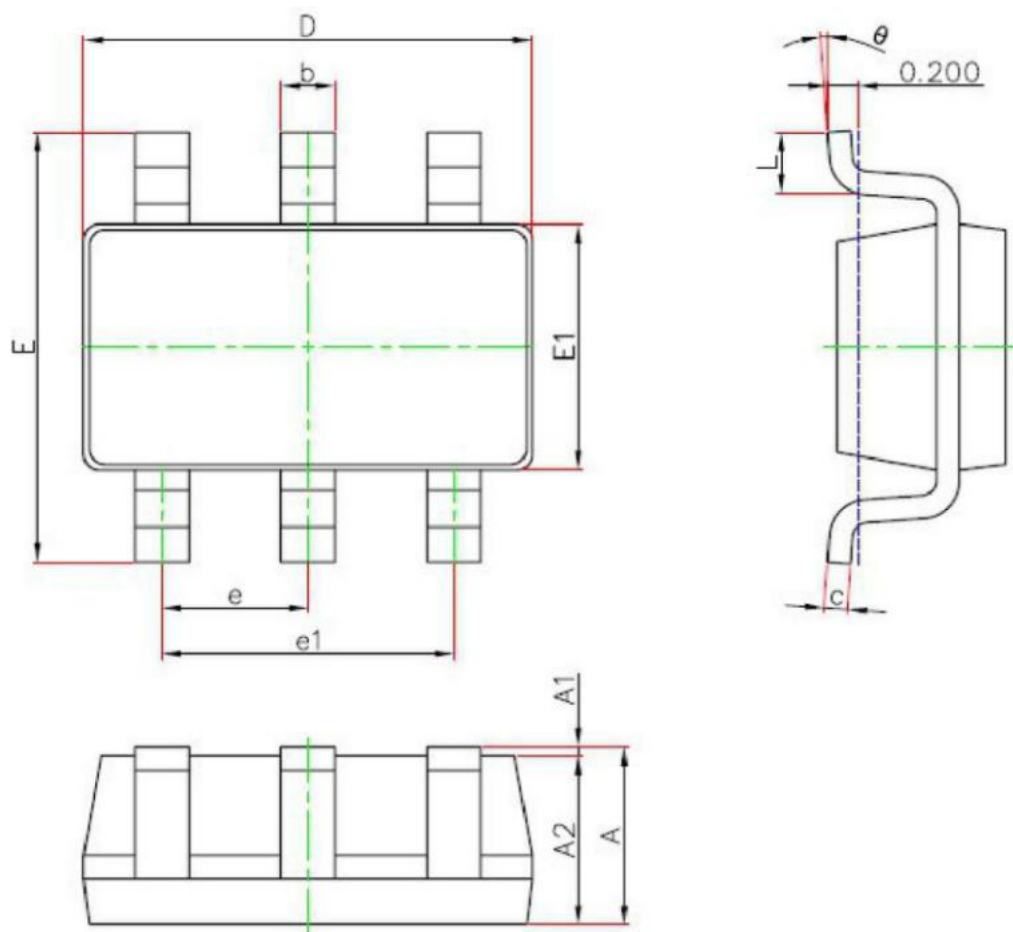


Figure9. Normalized Maximum Transient Thermal Impedance

SOT23-6 Package Information



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max.	Min.	Max.
A	1.050	1.250	0.041	0.049
A1	0.000	0.100	0.000	0.004
A2	1.050	1.150	0.041	0.045
b	0.300	0.500	0.012	0.020
c	0.100	0.200	0.004	0.008
D	2.820	3.020	0.111	0.119
E1	1.500	1.700	0.059	0.067
E	2.650	2.950	0.104	0.116
e	0.950(BSC)		0.037(BSC)	
e1	1.800	2.000	0.071	0.079
L	0.300	0.600	0.012	0.024
θ	0°	8°	0°	8°

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